

In the Application of:  
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Serial No.: New Application

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**IN THE SPECIFICATION**

(The specification enclosed with the original filing documents is a translation of the priority document that has been re-formatted to include section headings and paragraph numbers. No new matter has been added. Amendments presented herein are to this version of the specification.)

Please replace paragraphs 0046 and 0047 with the following:

[0046] Another aspect of the invention is a process for microtomy with steps that include: (a) holding at least one portion of the processed object by a support (3) of a holding device, (b) at least partially severing the processed object by a cutting device, preferably a laser cutting device wherein laser radiation (11) is released from a radiation source (10) which is assigned to the cutting device, and this laser radiation is focussed and the beam focus (22) is routed in a sequence of pulses to a location of the parting surface (19, 22) of the processed object in order to produce material severing at this site, the beam focus (22) relative to the support (3) being moved in two or three directions of space so that the processed object is microtomed. ~~the features as claimed in claim 14.~~ The process is especially suited to being executed with the microtome ~~as claimed in the~~ of the present invention.

[0047] Some advantageous forms of the process are given in the claims 15-22 and correspond to execution of the process by means of advantageous embodiments of the microtome as claimed in the invention. Reference is made to the description above in this respect.